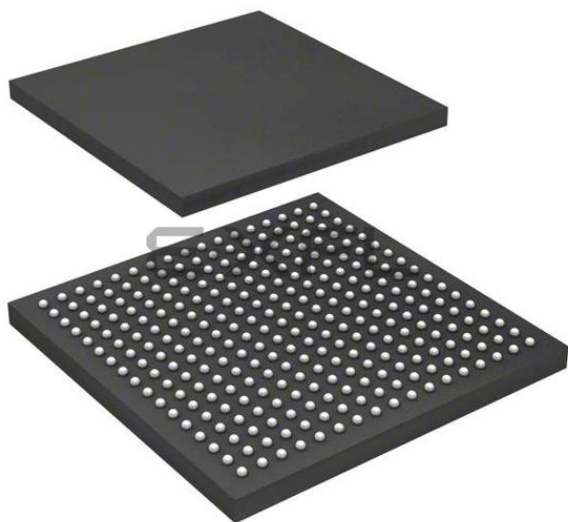




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Understanding [Embedded - Microprocessors](#)

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of [Embedded - Microprocessors](#)

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details

Product Status	Active
Core Processor	ARM® Cortex®-A5
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	500MHz
Co-Processors/DSP	Multimedia; NEON™ MPE
RAM Controllers	LPDDR1, LPDDR2, LPDDR3, DDR2, DDR3, DDR3L, QSPI
Graphics Acceleration	Yes
Display & Interface Controllers	Keyboard, LCD, Touchscreen
Ethernet	10/100Mbps (1)
SATA	-
USB	USB 2.0 + HSIC
Voltage - I/O	3.3V
Operating Temperature	-40°C ~ 85°C (TA)
Security Features	ARM TZ, Boot Security, Cryptography, RTIC, Secure Fusebox, Secure JTAG, Secure Memory, Secure RTC
Package / Case	289-LFBGA
Supplier Device Package	289-LFBGA (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsama5d28c-d1g-cu

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1. Features

- ARM Cortex-A5 core
 - ARMv7-A architecture
 - ARM TrustZone
 - NEON™ Media Processing Engine
 - Up to 500 MHz
 - ETM/ETB 8 Kbytes
- Memory Architecture
 - Memory Management Unit
 - 32-Kbyte L1 data cache, 32-Kbyte L1 instruction cache
 - 128-Kbyte L2 cache configurable to be used as an internal SRAM
 - DDR2-SDRAM memory up to 1 Gb
 - One 128-Kbyte scrambled internal SRAM
 - One 160-Kbyte internal ROM
 - 64-Kbyte scrambled and maskable ROM embedding boot loader/Secure boot loader
 - 96-Kbyte unscrambled, unmaskable ROM for NAND Flash BCH ECC table
 - High-bandwidth scramblable 16-bit Double Data Rate (DDR) multiport dynamic RAM controller supporting Winbond DDR2-SDRAM up to 1 Gb , including “on-the-fly” encryption/decryption path
 - 8-bit SLC/MLC NAND controller, with up to 32-bit Error Correcting Code (PMECC)
- System running up to 166 MHz
 - Reset controller, shutdown controller, periodic interval timer, independent watchdog timer and secure Real-Time Clock (RTC) with clock calibration
 - One 600 to 1200 MHz PLL for the system and one 480 MHz PLL optimized for USB high speed
 - Digital fractional PLL for audio (11.2896 MHz and 12.288 MHz)
 - Internal low-power 12 MHz RC and 32 KHz typical RC
 - Selectable 32.768-Hz low-power oscillator and 8 to 24 MHz oscillator
 - 51 DMA Channels including two 16-channel 64-bit Central DMA Controllers
 - 64-bit Advanced Interrupt Controller (AIC)
 - 64-bit Secure Advanced Interrupt Controller (SAIC)
 - Three programmable external clock signals
- Low-Power Modes
 - Ultra Low-power mode with fast wakeup capability
 - Low-power Backup mode with 5-Kbyte SRAM and SleepWalking™ features
 - Wakeup from up to nine wakeup pins, UART reception, analog comparison
 - Fast wakeup capability
 - Extended Backup mode with DDR2-SDRAM in Self-Refresh mode
- Peripherals
 - LCD TFT controller up to 1024x768, with four overlays, rotation, post-processing and alpha blending, 24-bit parallel RGB

- Up to eight tamper pins for static or dynamic intrusion detections
- Environmental monitors on specific versions: temperature, voltage, frequency and active die shield⁽¹⁾
- Secure Boot Loader⁽²⁾
- On-the-fly AES encryption/decryption on DDR2-SDRAM and QSPI memories (AESB)
- RTC including time-stamping on security intrusions
- Programmable fuse box with 544 fuse bits (including JTAG protection and BMS)
- Hardware cryptography
 - SHA (SHA1, SHA224, SHA256, SHA384, SHA512): compliant with FIPS PUB 180-2
 - AES: 256-, 192-, 128-bit key algorithm, compliant with FIPS PUB 197
 - TDES: two-key or three-key algorithms, compliant with FIPS PUB 46-3
 - True Random Number Generator (TRNG) compliant with NIST Special Publication 800-22 Test Suite and FIPS PUBs 140-2 and 140-3
- Up to 128 I/Os
 - Fully programmable through set/clear registers
 - Multiplexing of up to eight peripheral functions per I/O line
 - Each I/O line can be assigned to a peripheral or used as a general purpose I/O
 - PIO controller features a synchronous output providing up to 32 bits of data output in one write operation

Note:

1. For environmental monitors, refer to the document *SAMA5D23 and SAMA5D28 Environmental Monitors* (document no. 44036), available under Non-Disclosure Agreement (NDA). Contact a Microchip sales representative for details.
2. For secure boot strategies, refer to the document *SAMA5D2 Series Secure Boot Strategy* (document no. 44040), available under Non-Disclosure Agreement (NDA). Contact a Microchip sales representative for details.

3. Configuration Summary

Table 3-1. Configuration Summary

Feature	SAMA5D225	SAMA5D27		SAMA5D28
Package	TFBGA196	TFBGA289		
DDR2-SDRAM	128 Mb	512 Mb	1 Gb	1 Gb
SMC	Up to 16-bit			
Internal Memory Bus Width	16-bit			
PIOs	90	128		
SRAM	128 Kbytes			
QSPI	2			
LCD	24-bit RGB			
Camera Interface (ISC)	1			
EMAC	1			
PTC	4 X-lines x 8 Y-lines	8 X-lines x 8 Y-lines		
CAN	1	2		
USB	2 (2 Hosts or 1 Host/1 Device)	3 (2 Hosts/1 HSIC or 1 Host/1 Device/1 HSIC)		
UART/SPI/I ² C	9 / 7 / 7	10 / 7 / 7		
SDIO/SD/MMC	2			
I ² S/SSC/Class D/PDM	2 / 2 / 1 / 1			
ADC Inputs	5	12		
Timers	5	6		
PWM	4 (PWM) + 5 (TC)	4 (PWM) + 6 (TC)		
Tamper Pins	6	8		
AESB	Yes			
Environmental Monitors, Die Shield	–	–		Yes

4. Chip Identifier

Table 4-1. SAMA5D2 SIP Chip ID Registers

Chip Name	CHIPID_CIDR	CHIPID_EXID
SAMA5D225C-D1M	0x8A5C08C2	0x00000053
SAMA5D27C-D5M		0x00000032
SAMA5D27C-D1G		0x00000033
SAMA5D28C-D1G		0x00000013

5. Package and Ballout

The SAMA5D2 SIP is available in the packages listed below.



Important: SAMA5D2 SIP devices are not pin-to-pin compatible with SAMA5D2 devices.

For mechanical characteristics of the TFBGA196, refer to the SAMA5D2 Series Datasheet, ref. no. DS60001476, available via www.microchip.com.

For mechanical characteristics of the TFBGA289, see [Mechanical Characteristics](#).

Table 5-1. Packages

Package Name	Ball Count	Ball Pitch	Package Size
TFBGA196	196	0.75 mm	11 x 11 (mm)
TFBGA289	289	0.8 mm	14 x 14 (mm)

Table 5-2. Ball Description

289-ball BGA	196-ball BGA	Power Rail	I/O Type	Primary		Alternate		PIO Peripheral				Reset State (Signal, Dir, PU, PD, HiZ, ST) ⁽¹⁾
				Signal	Dir	Signal	Dir	Func	Signal	Dir	IO Set	
U13	M8	VDDSDMMC	GPIO_EMMC	PA0	I/O	–	–	A	SDMMC0_CK	I/O	1	PIO, I, PU, ST
								B	QSPI0_SCK	O	1	
								F	D0	I/O	2	
N7	F7	VDDSDMMC	GPIO_EMMC	PA1	I/O	–	–	A	SDMMC0_CMD	I/O	1	PIO, I, PU, ST
								B	QSPI0_CS	O	1	
								F	D1	I/O	2	
U14	L8	VDDSDMMC	GPIO_EMMC	PA2	I/O	–	–	A	SDMMC0_DAT0	I/O	1	PIO, I, PU, ST
								B	QSPI0_IO0	I/O	1	
								F	D2	I/O	2	
T13	G8	VDDSDMMC	GPIO_EMMC	PA3	I/O	–	–	A	SDMMC0_DAT1	I/O	1	PIO, I, PU, ST
								B	QSPI0_IO1	I/O	1	
								F	D3	I/O	2	
U15	K8	VDDSDMMC	GPIO_EMMC	PA4	I/O	–	–	A	SDMMC0_DAT2	I/O	1	PIO, I, PU, ST
								B	QSPI0_IO2	I/O	1	
								F	D4	I/O	2	
U16	P9	VDDSDMMC	GPIO_EMMC	PA5	I/O	–	–	A	SDMMC0_DAT3	I/O	1	PIO, I, PU, ST
								B	QSPI0_IO3	I/O	1	
								F	D5	I/O	2	
U17	P10	VDDSDMMC	GPIO_EMMC	PA6	I/O	–	–	A	SDMMC0_DAT4	I/O	1	PIO, I, PU, ST
								B	QSPI1_SCK	O	1	
								D	TIOA5	I/O	1	
								E	FLEXCOM2_IO0	I/O	1	

289-ball BGA	196-ball BGA	Power Rail	I/O Type	Primary		Alternate		PIO Peripheral				Reset State (Signal, Dir, PU, PD, HiZ, ST) ⁽¹⁾
				Signal	Dir	Signal	Dir	Func	Signal	Dir	IO Set	
								F	D6	I/O	2	
R11	P11	VDDSDMMC	GPIO_EMMC	PA7	I/O	–	–	A	SDMMC0_DAT5	I/O	1	PIO, I, PU, ST
								B	QSPI1_IO0	I/O	1	
								D	TIOB5	I/O	1	
								E	FLEXCOM2_IO1	I/O	1	
								F	D7	I/O	2	
R9	K9	VDDSDMMC	GPIO_EMMC	PA8	I/O	–	–	A	SDMMC0_DAT6	I/O	1	PIO, I, PU, ST
								B	QSPI1_IO1	I/O	1	
								D	TCLK5	I	1	
								E	FLEXCOM2_IO2	I/O	1	
								F	NWE/NANDWE	O	2	
P8	J9	VDDSDMMC	GPIO_EMMC	PA9	I/O	–	–	A	SDMMC0_DAT7	I/O	1	PIO, I, PU, ST
								B	QSPI1_IO2	I/O	1	
								D	TIOA4	I/O	1	
								E	FLEXCOM2_IO3	O	1	
								F	NCS3	O	2	
R10	N14	VDDSDMMC	GPIO_EMMC	PA10	I/O	–	–	A	SDMMC0_RSTN	O	1	PIO, I, PU, ST
								B	QSPI1_IO3	I/O	1	
								D	TIOB4	I/O	1	
								E	FLEXCOM2_IO4	O	1	
								F	A21/NANDALE	O	2	
P15	N13	VDDIOP1	GPIO	PA11	I/O	–	–	A	SDMMC0_1V8SEL	O	1	PIO, I, PU, ST
								B	QSPI1_CS	O	1	
								D	TCLK4	I	1	
								F	A22/NANDCLE	O	2	
N17	L12	VDDIOP1	GPIO	PA12	I/O	–	–	A	SDMMC0_WP	I	1	PIO, I, PU, ST
								B	IRQ	I	1	
								F	NRD/NANDOE	O	2	
P16	M14	VDDIOP1	GPIO	PA13	I/O	–	–	A	SDMMC0_CD	I	1	PIO, I, PU, ST
								E	FLEXCOM3_IO1	I/O	1	
								F	D8	I/O	2	
M17	J10	VDDIOP1	GPIO_QSPI	PA14	I/O	–	–	A	SPI0_SPCK	I/O	1	PIO, I, PU, ST
								B	TK1	I/O	1	
								C	QSPI0_SCK	O	2	
								D	I2SC1_MCK	O	2	
								E	FLEXCOM3_IO2	I/O	1	
								F	D9	I/O	2	
N16	L14	VDDIOP1	GPIO	PA15	I/O	–	–	A	SPI0_MOSI	I/O	1	PIO, I, PU, ST
								B	TF1	I/O	1	
								C	QSPI0_CS	O	2	
								D	I2SC1_CK	I/O	2	

289-ball BGA	196-ball BGA	Power Rail	I/O Type	Primary		Alternate		PIO Peripheral				Reset State (Signal, Dir, PU, PD, HiZ, ST) ⁽¹⁾
				Signal	Dir	Signal	Dir	Func	Signal	Dir	IO Set	
								E	FLEXCOM3_IO0	I/O	1	
								F	D10	I/O	2	
M11	H14	VDDIOP1	GPIO_IO	PA16	I/O	–	–	A	SPI0_MISO	I/O	1	PIO, I, PU, ST
								B	TD1	O	1	
								C	QSPI0_IO0	I/O	2	
								D	I2SC1_WS	I/O	2	
								E	FLEXCOM3_IO3	O	1	
								F	D11	I/O	2	
N14	K14	VDDIOP1	GPIO_IO	PA17	I/O	–	–	A	SPI0_NPCS0	I/O	1	PIO, I, PU, ST
								B	RD1	I	1	
								C	QSPI0_IO1	I/O	2	
								D	I2SC1_DI0	I	2	
								E	FLEXCOM3_IO4	O	1	
								F	D12	I/O	2	
T16	L9	VDDIOP1	GPIO_IO	PA18	I/O	–	–	A	SPI0_NPCS1	O	1	PIO, I, PU, ST
								B	RK1	I/O	1	
								C	QSPI0_IO2	I/O	2	
								D	I2SC1_DO0	O	2	
								E	SDMMC1_DAT0	I/O	1	
								F	D13	I/O	2	
T15	P12	VDDIOP1	GPIO_IO	PA19	I/O	–	–	A	SPI0_NPCS2	O	1	PIO, I, PU, ST
								B	RF1	I/O	1	
								C	QSPI0_IO3	I/O	2	
								D	TIOA0	I/O	1	
								E	SDMMC1_DAT1	I/O	1	
								F	D14	I/O	2	
P9	H9	VDDIOP1	GPIO_IO	PA20	I/O	–	–	A	SPI0_NPCS3	O	1	PIO, I, PU, ST
								D	TIOB0	I/O	1	
								E	SDMMC1_DAT2	I/O	1	
								F	D15	I/O	2	
P10	G9	VDDIOP1	GPIO_IO	PA21	I/O	–	–	A	IRQ	I	2	PIO, I, PU, ST
								B	PCK2	O	3	
								D	TCLK0	I	1	
								E	SDMMC1_DAT3	I/O	1	
								F	NANDRDY	I	2	
T17	K10	VDDIOP1	GPIO_QSPI	PA22	I/O	–	–	A	FLEXCOM1_IO2	I/O	1	PIO, I, PU, ST
								B	D0	I/O	1	
								C	TCK	I	4	
								D	SPI1_SPCK	I/O	2	
								E	SDMMC1_CK	I/O	1	
								F	QSPI0_SCK	O	3	

289-ball BGA	196-ball BGA	Power Rail	I/O Type	Primary		Alternate		PIO Peripheral				Reset State (Signal, Dir, PU, PD, HiZ, ST) ⁽¹⁾
				Signal	Dir	Signal	Dir	Func	Signal	Dir	IO Set	
								C	TD1	O	2	
								D	I2SC1_WS	I/O	1	
								E	QSPI1_IO0	I/O	3	
								F	GRXDV	I	3	
C4	A5	VDDIOP0	GPIO_IO	PB17	I/O	–	–	A	LCDDAT6	O	1	PIO, I, PU, ST
								B	A6	O	1	
								C	RD1	I	2	
								D	I2SC1_DI0	I	1	
								E	QSPI1_IO1	I/O	3	
								F	GRXER	I	3	
A5	B4	VDDIOP0	GPIO_IO	PB18	I/O	–	–	A	LCDDAT7	O	1	PIO, I, PU, ST
								B	A7	O	1	
								C	RK1	I/O	2	
								D	I2SC1_DO0	O	1	
								E	QSPI1_IO2	I/O	3	
								F	GRX0	I	3	
B4	A6	VDDIOP0	GPIO_IO	PB19	I/O	–	–	A	LCDDAT8	O	1	PIO, I, PU, ST
								B	A8	O	1	
								C	RF1	I/O	2	
								D	TIOA3	I/O	2	
								E	QSPI1_IO3	I/O	3	
								F	GRX1	I	3	
A4	A4	VDDIOP0	GPIO	PB20	I/O	–	–	A	LCDDAT9	O	1	PIO, I, PU, ST
								B	A9	O	1	
								C	TK0	I/O	1	
								D	TIOB3	I/O	2	
								E	PCK1	O	4	
								F	GTX0	O	3	
D3	A3	VDDIOP0	GPIO	PB21	I/O	–	–	A	LCDDAT10	O	1	PIO, I, PU, ST
								B	A10	O	1	
								C	TF0	I/O	1	
								D	TCLK3	I	2	
								E	FLEXCOM3_IO2	I/O	3	
								F	GTX1	O	3	
C3	D3	VDDIOP0	GPIO	PB22	I/O	–	–	A	LCDDAT11	O	1	PIO, I, PU, ST
								B	A11	O	1	
								C	TD0	O	1	
								D	TIOA2	I/O	2	
								E	FLEXCOM3_IO1	I/O	3	
								F	GMDC	O	3	
B3	B2	VDDIOP0	GPIO	PB23	I/O	–	–	A	LCDDAT12	O	1	PIO, I, PU, ST

289-ball BGA	196-ball BGA	Power Rail	I/O Type	Primary		Alternate		PIO Peripheral				Reset State (Signal, Dir, PU, PD, HiZ, ST) ⁽¹⁾
				Signal	Dir	Signal	Dir	Func	Signal	Dir	IO Set	
								B	A12	O	1	
								C	RD0	I	1	
								D	TIOB2	I/O	2	
								E	FLEXCOM3_IO0	I/O	3	
								F	GMDIO	I/O	3	
E2	E3	VDDIOP0	GPIO	PB24	I/O	–	–	A	LCDDAT13	O	1	PIO, I, PU, ST
								B	A13	O	1	
								C	RK0	I/O	1	
								D	TCLK2	I	2	
								E	FLEXCOM3_IO3	O	3	
								F	ISC_D10	I	3	
A3	E2	VDDIOP0	GPIO	PB25	I/O	–	–	A	LCDDAT14	O	1	PIO, I, PU, ST
								B	A14	O	1	
								C	RF0	I/O	1	
								E	FLEXCOM3_IO4	O	3	
								F	ISC_D11	I	3	
G3	D4	VDDIOP0	GPIO	PB26	I/O	–	–	A	LCDDAT15	O	1	PIO, I, PU, ST
								B	A15	O	1	
								C	URXD0	I	1	
								D	PDMIC_DAT		1	
								F	ISC_D0	I	3	
F4	C3	VDDIOP0	GPIO	PB27	I/O	–	–	A	LCDDAT16	O	1	PIO, I, PU, ST
								B	A16	O	1	
								C	UTXD0	O	1	
								D	PDMIC_CLK		1	
								F	ISC_D1	I	3	
D2	D2	VDDIOP0	GPIO	PB28	I/O	–	–	A	LCDDAT17	O	1	PIO, I, PU, ST
								B	A17	O	1	
								C	FLEXCOM0_IO0	I/O	1	
								D	TIOA5	I/O	2	
								F	ISC_D2	I	3	
G8	B3	VDDIOP0	GPIO	PB29	I/O	–	–	A	LCDDAT18	O	1	PIO, I, PU, ST
								B	A18	O	1	
								C	FLEXCOM0_IO1	I/O	1	
								D	TIOB5	I/O	2	
								F	ISC_D3	I	3	
C2	F3	VDDIOP0	GPIO	PB30	I/O	–	–	A	LCDDAT19	O	1	PIO, I, PU, ST
								B	A19	O	1	
								C	FLEXCOM0_IO2	I/O	1	
								D	TCLK5	I	2	
								F	ISC_D4	I	3	

289-ball BGA	196-ball BGA	Power Rail	I/O Type	Primary		Alternate		PIO Peripheral				Reset State (Signal, Dir, PU, PD, HiZ, ST) ⁽¹⁾
				Signal	Dir	Signal	Dir	Func	Signal	Dir	IO Set	
G7	A2	VDDIOP0	GPIO	PB31	I/O	–	–	A	LCDDAT20	O	1	PIO, I, PU, ST
								B	A20	O	1	
								C	FLEXCOM0_IO3	O	1	
								D	TWD0	I/O	1	
								F	ISC_D5	I	3	
N10	L13	VDDIOP1	GPIO	PC0	I/O	–	–	A	LCDDAT21	O	1	PIO, I, PU, ST
								B	A23	O	1	
								C	FLEXCOM0_IO4	O	1	
								D	TWCK0	I/O	1	
								F	ISC_D6	I	3	
N11	H11	VDDIOP1	GPIO	PC1	I/O	–	–	A	LCDDAT22	O	1	PIO, I, PU, ST
								B	A24	O	1	
								C	CANTX0	O	1	
								D	SPI1_SPCK	I/O	1	
								E	I2SC0_CK	I/O	1	
								F	ISC_D7	I	3	
N9	L11	VDDIOP1	GPIO	PC2	I/O	–	–	A	LCDDAT23	O	1	PIO, I, PU, ST
								B	A25	O	1	
								C	CANRX0	I	1	
								D	SPI1_MOSI	I/O	1	
								E	I2SC0_MCK	O	1	
								F	ISC_D8	I	3	
M10	F13	VDDIOP1	GPIO	PC3	I/O	–	–	A	LCDPWM	O	1	PIO, I, PU, ST
								B	NWAIT	I	1	
								C	TIOA1	I/O	1	
								D	SPI1_MISO	I/O	1	
								E	I2SC0_WS	I/O	1	
								F	ISC_D9	I	3	
N15	G14	VDDIOP1	GPIO	PC4	I/O	–	–	A	LCDDISP	O	1	PIO, I, PU, ST
								B	NWR1/NBS1	O	1	
								C	TIOB1	I/O	1	
								D	SPI1_NPCS0	I/O	1	
								E	I2SC0_DI0	I	1	
								F	ISC_PCK	I	3	
M16	J14	VDDIOP1	GPIO	PC5	I/O	–	–	A	LCDVSYNC	O	1	PIO, I, PU, ST
								B	NCS0	O	1	
								C	TCLK1	I	1	
								D	SPI1_NPCS1	O	1	
								E	I2SC0_DO0	O	1	
								F	ISC_VSYNC	I	3	
L11	J13	VDDIOP1	GPIO	PC6	I/O	–	–	A	LCDHSYNC	O	1	PIO, I, PU, ST

289-ball BGA	196-ball BGA	Power Rail	I/O Type	Primary		Alternate		PIO Peripheral				Reset State (Signal, Dir, PU, PD, HiZ, ST) ⁽¹⁾
				Signal	Dir	Signal	Dir	Func	Signal	Dir	IO Set	
G5	–	VDDISC	GPIO	PC14	I/O	–	–	E	TF0	I/O	2	PIO, I, PU, ST
								F	A2	O	2	
								A	LCDDAT6	O	2	
								B	GRX0	I	1	
								C	ISC_D5	I	1	
								E	TD0	O	2	
G2	–	VDDISC	GPIO	PC15	I/O	–	–	F	A3	O	2	PIO, I, PU, ST
								A	LCDDAT7	O	2	
								B	GRX1	I	1	
								C	ISC_D6	I	1	
								E	RD0	I	2	
								F	A4	O	2	
G6	–	VDDISC	GPIO	PC16	I/O	–	–	A	LCDDAT10	O	2	PIO, I, PU, ST
								B	GTx0	O	1	
								C	ISC_D7	I	1	
								E	RK0	I/O	2	
								F	A5	O	2	
								A	LCDDAT11	O	2	PIO, I, PU, ST
C1	–	VDDISC	GPIO	PC17	I/O	–	–	B	GTx1	O	1	
								C	ISC_D8	I	1	
								E	RF0	I/O	2	
								F	A6	O	2	
								A	LCDDAT12	O	2	PIO, I, PU, ST
G9	–	VDDISC	GPIO	PC18	I/O	–	–	B	GMDC	O	1	
								C	ISC_D9	I	1	
								E	FLEXCOM3_IO2	I/O	2	
								F	A7	O	2	
								A	LCDDAT13	O	2	PIO, I, PU, ST
D1	–	VDDISC	GPIO	PC19	I/O	–	–	B	GMDIO	I/O	1	
								C	ISC_D10	I	1	
								E	FLEXCOM3_IO1	I/O	2	
								F	A8	O	2	
								A	LCDDAT14	O	2	PIO, I, PU, ST
H4	–	VDDISC	GPIO	PC20	I/O	–	–	B	GRXCK	I	1	
								C	ISC_D11	I	1	
								E	FLEXCOM3_IO0	I/O	2	
								F	A9	O	2	
								A	LCDDAT15	O	2	PIO, I, PU, ST
E1	–	VDDISC	GPIO	PC21	I/O	–	–	B	GTxER	O	1	
								C	ISC_PCK	I	1	
								E	FLEXCOM3_IO3	O	2	

289-ball BGA	196-ball BGA	Power Rail	I/O Type	Primary		Alternate		PIO Peripheral				Reset State (Signal, Dir, PU, PD, HiZ, ST) ⁽¹⁾
				Signal	Dir	Signal	Dir	Func	Signal	Dir	IO Set	
E7	–	VDDIOP2	GPIO_CLK	PD0	I/O	–	–	C	URXD3	I	2	PIO, I, PU, ST
								F	A20	O	2	
								A	LCDPCK	O	2	
								B	FLEXCOM4_IO4	O	1	
								C	UTXD3	O	2	
								D	GTSUCOMP	O	2	
C9	–	VDDIOP2	GPIO	PD1	I/O	–	–	F	A23	O	2	PIO, I, PU, ST
								A	LCDDEN	O	2	
								D	GRXCK	I	2	
D8	–	VDDIOP2	GPIO_CLK	PD2	I/O	–	–	F	A24	O	2	PIO, I, PU, ST
								A	URXD1	I	1	
								D	GTXER	O	2	
								E	ISC_MCK	O	2	
J1	–	VDDANA	GPIO_AD	PD3	I/O	–	–	F	A25	O	2	PIO, I, PU, ST
								A	UTXD1	O	1	
								B	FIQ	I	2	
								D	GCRS	I	2	
								E	ISC_D11	I	2	
H7	–	VDDANA	GPIO_AD	PD4	I/O	–	–	F	NWAIT	I	2	PIO, I, PU, ST
								A	TWD1	I/O	2	
								B	URXD2	I	1	
								D	GCOL	I	2	
								E	ISC_D10	I	2	
H1	–	VDDANA	GPIO_AD	PD5	I/O	–	–	F	NCS0	O	2	PIO, I, PU, ST
								A	TWCK1	I/O	2	
								B	UTXD2	O	1	
								D	GRX2	I	2	
								E	ISC_D9	I	2	
J2	–	VDDANA	GPIO_AD	PD6	I/O	–	–	F	NCS1	O	2	PIO, I, PU, ST
								A	TCK	I	2	
								B	PCK1	O	1	
								D	GRX3	I	2	
								E	ISC_D8	I	2	
H6	H5	VDDANA	GPIO_AD	PD7	I/O	–	–	F	NCS2	O	2	PIO, I, PU, ST
								A	TDI	I	2	
								C	UTMI_RXVAL	O	1	
								D	GTX2	O	2	
								E	ISC_D0	I	2	
K3	J2	VDDANA	GPIO_AD	PD8	I/O	–	–	F	NWR1/NBS1	O	2	PIO, I, PU, ST
								A	TDO	O	2	
								C	UTMI_RXERR	O	1	

289-ball BGA	196-ball BGA	Power Rail	I/O Type	Primary		Alternate		PIO Peripheral				Reset State (Signal, Dir, PU, PD, HiZ, ST) ⁽¹⁾
				Signal	Dir	Signal	Dir	Func	Signal	Dir	IO Set	
L1	J1	VDDANA	GPIO_AD	PD16	I/O	–	–	A	TDO	O	1	PIO, I, PU, ST
								B	FLEXCOM4_IO4	O	2	
								C	UTMI_CDRBISTEN	I	1	
								D	GTx1	O	2	
								E	ISC_VSYNC	I	2	
								F	ISC_D8	I	4	
K1	A1	VDDANA	GPIO_AD	PD17	I/O	–	–	A	TMS	I	1	A, PU, ST
								C	UTMI_CDRCPSELDIV	O	1	
								D	GMDC	O	2	
								E	ISC_HSYNC	I	2	
								F	ISC_D9	I	4	
J7	G3	VDDANA	GPIO_AD	PD18	I/O	–	–	A	NTRST	I	1	PIO, I, PU, ST
								D	GMDIO	I/O	2	
								E	ISC_FIELD	I	2	
								F	ISC_D10	I	4	
L8	K2	VDDANA	GPIO_AD	PD19	I/O	AD0	–	A	PCK0	O	1	PIO, I, PU, ST
								B	TWD1	I/O	3	
								C	URXD2	I	3	
								E	I2SC0_CK	I/O	2	
								F	ISC_D11	I	4	
L2	H1	VDDANA	GPIO_AD	PD20	I/O	AD1	–	A	TIOA2	I/O	3	PIO, I, PU, ST
								B	TWCK1	I/O	3	
								C	UTXD2	O	3	
								E	I2SC0_MCK	O	2	
								F	ISC_PCK	I	4	
P1	G1	VDDANA	GPIO_AD	PD21	I/O	AD2	–	A	TIOB2	I/O	3	PIO, I, PU, ST
								B	TWD0	I/O	4	
								C	FLEXCOM4_IO0	I/O	3	
								E	I2SC0_WS	I/O	2	
								F	ISC_VSYNC	I	4	
L6	F1	VDDANA	GPIO_AD	PD22	I/O	AD3	–	A	TCLK2	I	3	PIO, I, PU, ST
								B	TWCK0	I/O	4	
								C	FLEXCOM4_IO1	I/O	3	
								E	I2SC0_DI0	I	2	
								F	ISC_HSYNC	I	4	
T1	E1	VDDANA	GPIO_AD	PD23	I/O	AD4	–	A	URXD2	I	2	PIO, I, PU, ST
								C	FLEXCOM4_IO2	I/O	3	
								E	I2SC0_DO0	O	2	
								F	ISC_FIELD	I	4	
L4	–	VDDANA	GPIO_AD	PD24	I/O	AD5	–	A	UTXD2	O	2	PIO, I, PU, ST
								C	FLEXCOM4_IO3	O	3	

289-ball BGA	196-ball BGA	Power Rail	I/O Type	Primary		Alternate		PIO Peripheral				Reset State (Signal, Dir, PU, PD, HiZ, ST) ⁽¹⁾	
				Signal	Dir	Signal	Dir	Func	Signal	Dir	IO Set		
D6	–	GNDIOP2	ground	GNDIOP2	I	–	–	–	–	–	–	–	
N8	J7	VDDSDMMC	power	VDDSDMMC	I	–	–	–	–	–	–	–	
R8	J8	GNDSDMMC	ground	GNDSDMMC	I	–	–	–	–	–	–	–	
H3	–	VDDISC	power	VDDISC	I	–	–	–	–	–	–	–	
H5	–	GNDISC	ground	GNDISC	I	–	–	–	–	–	–	–	
N13	M13	VDDFUSE	power	VDDFUSE	I	–	–	–	–	–	–	–	
R5	P4	VDDPLLA	power	VDDPLLA	I	–	–	–	–	–	–	–	
T5	L6	GNDPLLA	ground	GNDPLLA	I	–	–	–	–	–	–	–	
M4	K6	VDDAUDIOPLL	power	VDDAUDIOPLL	I	–	–	–	–	–	–	–	
T3	J6	GNDDPLL	ground	GNDDPLL	I	–	–	–	–	–	–	–	
T4	H6	GNDAUDIOPL L	ground	GNDAUDIOPLL	I	–	–	–	–	–	–	–	
T8	P1	VDDAUDIOPLL	–	CLK_AUDIO	–	–	–	–	–	–	–	–	
U9	N5	VDDOSC	–	XIN	–	–	–	–	–	–	–	–	
U8	P5	VDDOSC	–	XOUT	–	–	–	–	–	–	–	–	
N6	M7	VDDOSC	–	VDDOSC	–	–	–	–	–	–	–	–	
P5	N6	GNDOSC	power	GNDOSC	I	–	–	–	–	–	–	–	
P6	M6	VDDUTMII	power	VDDUTMII	I	–	–	–	–	–	–	–	
R7	–	VDDHSIC	power	VDDHSIC	I	–	–	–	–	–	–	–	
M6	L7	GNDUTMII	power	GNDUTMII	I	–	–	–	–	–	–	–	
U10	N7	VDDUTMII	–	HHSDPA	I	–	–	–	–	–	–	–	
T10	P7	VDDUTMII	–	HHSDMA	–	–	–	–	–	–	–	–	
U11	N8	VDDUTMII	–	HHSDPB	–	–	–	–	–	–	–	–	
T11	P8	VDDUTMII	–	HHSDMB	–	–	–	–	–	–	–	–	
T12	–	VDDHSIC	–	HHSDPDATC	–	–	–	–	–	–	–	–	
U12	–	VDDHSIC	–	HHSDMSTRC		–	–	–	–	–	–	–	
M7	K7	VDDUTMIC	power	VDDUTMIC	I	–	–	–	–	–	–	–	
R6	G5	GNDUTMIC	power	GNDUTMIC	I	–	–	–	–	–	–	–	
T6	P6	VDDUTMIC	–	VBG	–	–	–	–	–	–	–	–	
R4	D1	VDDBU	–	TST	–	–	–	–	–	–	–	–	
T7	J5	VDDBU	–	NRST	–	–	–	–	–	–	–	–	
R3	N3	VDDBU	–	JTAGSEL	–	–	–	–	–	–	–	–	
R2	N1	VDDBU	–	WKUP	–	–	–	–	–	–	–	–	
N2	–	VDDBU	–	RXD	–	–	–	–	–	–	–	–	
T2	B1	VDDBU	–	SHDN	–	–	–	–	–	–	–	–	
P3	N4	VDDBU	–	PIOBU0	–	–	–	–	–	–	–	–	
M3	L4	VDDBU	–	PIOBU1	–	–	–	–	–	–	–	–	
P2	M3	VDDBU	–	PIOBU2	–	–	–	–	–	–	–	–	
P4	M4	VDDBU	–	PIOBU3	–	–	–	–	–	–	–	–	
N4	J4	VDDBU	–	PIOBU4	–	–	–	–	–	–	–	–	
M5	M5	VDDBU	–	PIOBU5	–	–	–	–	–	–	–	–	
N5	–	VDDBU	–	PIOBU6	–	–	–	–	–	–	–	–	

6. DDR2-SDRAM Memory

The SAMA5D2 SIP is available with 128 Mbit, 512 Mbit or 1 Gbit DDR2-SDRAM memory options. For the features of these memories, see [DDR2-SDRAM Features](#).

For power consumption, electrical characteristics and timings of these memories, refer to the datasheets referenced below on the manufacturer's website www.winbond.com.

Table 6-1. Memory Datasheet References

Density	Winbond Packaged PN	Datasheet Reference Number
128 Mbit	W9712G6KB25I	W9712G6KB
512 Mbit	W9751G6KB25I	W9751G6KB
1 Gbit	W971GG6SB25I	W971GG6SB

8. Ordering Information

Table 8-1. Ordering Information

Ordering Code	MRL	Package	Carrier Type	Operating Temperature Range
ATSAMA5D225C-D1M-CU	C	BGA196	Tray	-40°C to +85°C
ATSAMA5D225C-D1M-CUR			Tape & Reel	
ATSAMA5D27C-D5M-CU		BGA289	Tray	
ATSAMA5D27C-D5M-CUR			Tape & Reel	
ATSAMA5D27C-D1G-CU			Tray	
ATSAMA5D27C-D1G-CUR			Tape & Reel	
ATSAMA5D28C-D1G-CU			Tray	
ATSAMA5D28C-D1G-CUR			Tape & Reel	

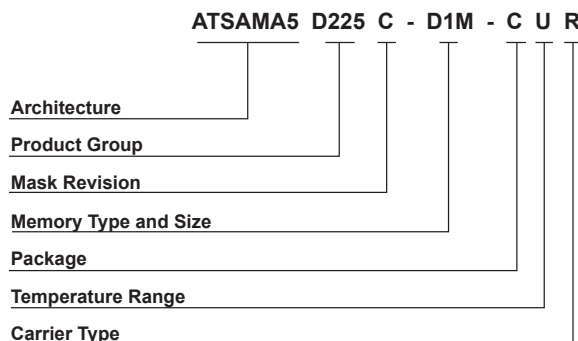
9. Revision History

Table 9-1. SAMA5D2 SIP Datasheet, DS60001484A, September-2017 Revision History

Changes
First issue.

Product Identification System

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.



Architecture:	ATSAM5	= ARM Cortex-A5 CPU
Product Group:	D225	= 196-ball general-purpose microprocessor family
	D27	= 289-ball general-purpose microprocessor family
	D28	= 289-ball general-purpose microprocessor family
Memory Type and Size:	D1M	= 128-Mbit DDR2 SDRAM
	D5M	= 512-Mbit DDR2 SDRAM
	D1G	= 1-Gigabit DDR2 SDRAM
Mask Revision:	C	
Package:	C	= BGA
Temperature Range:	U	= -40°C to +85°C (Industrial)
Carrier Type:	Blank	= Standard packaging (tray)
	R	= Tape and Reel

Examples:

- ATSAM5D225C-D1M-CU = ARM Cortex-A5 general-purpose microprocessor, 128-Mbit DDR2 SDRAM, 196-ball, Industrial temperature, BGA Package.

Note: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package

Microchip Devices Code Protection Feature

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the

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ISO/TS 16949

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